

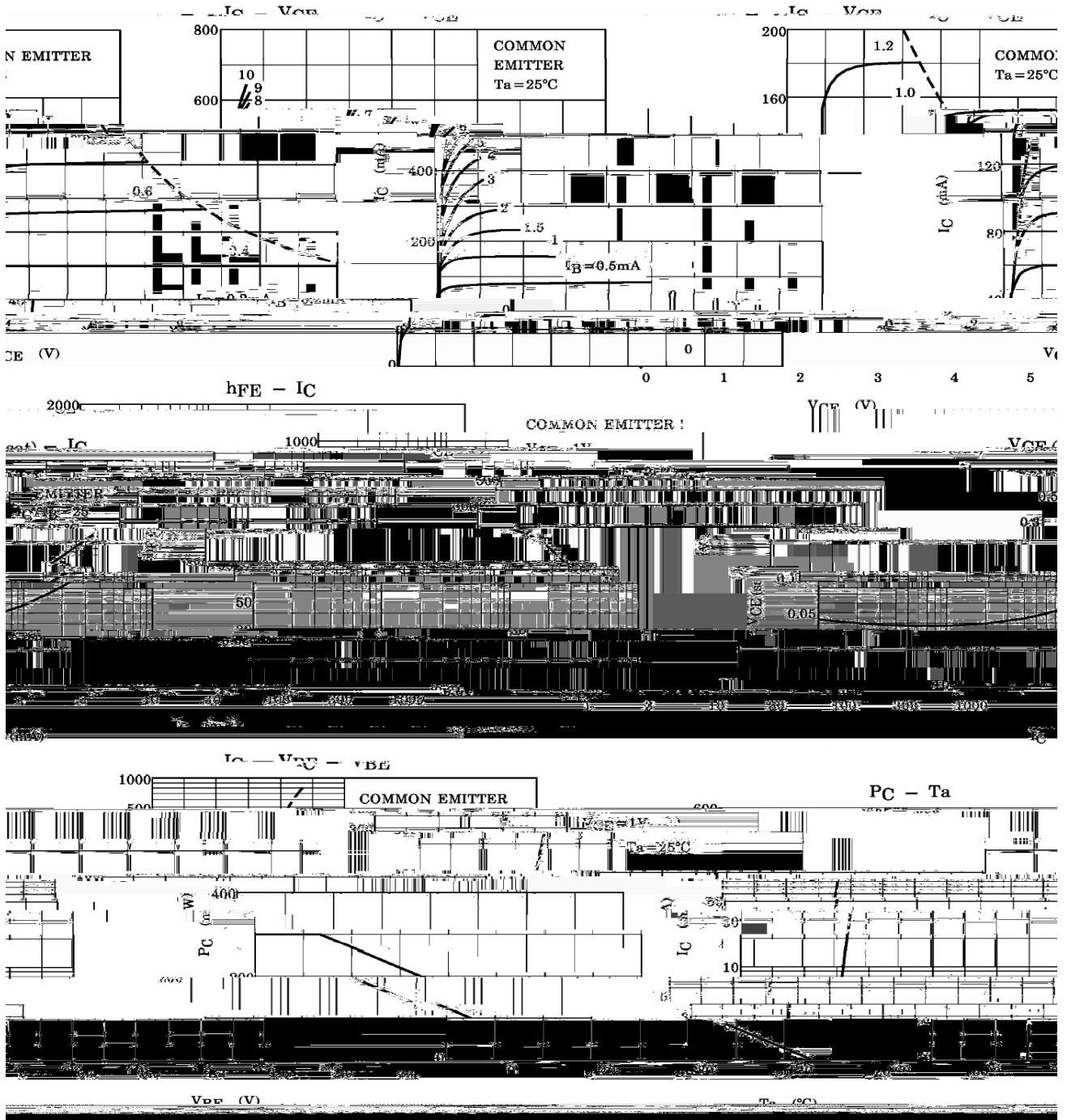


Parameter	Symbol	Rating	Unit
Collector to Base Voltage	$V_{CBO}$	35	V
Collector to Emitter Voltage	$V_{CEO}$	30	V
Emitter to Base Voltage	$V_{EBO}$	5.0	V
Collector Current - Continuous	$I_C$	800	mA
Base Current - Continuous	$I_B$	160	mA
Collector Power Dissipation	$P_C$	300	mW
Junction Temperature	$T_j$	150	
Storage Temperature Range	$T_{stg}$	-55 150	

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Collector to Emitter Breakdown Voltage	$V_{CEO}$	$I_C=10mA$ $I_B=0$	30			V
Collector Cut-Off Current	$I_{CBO}$	$V_{CB}=30V$ $I_E=0$			0.1	A
Emitter Cut-Off Current	$I_{EBO}$	$V_{EB}=5.0V$ $I_C=0$			0.1	A
DC Current Gain	$h_{FE(1)}$	$V_{CE}=1.0V$ $I_C=100mA$	100		320	
	$h_{FE(2)}$	$V_{CE}=1.0V$ $I_C=700mA$	35			
Collector-to-Emitter Saturation Voltage	$V_{CE(sat)}$	$I_C=500mA$ $I_B=20mA$			0.5	V
Base-to-Emitter Voltage	$V_{BE}$	$V_{CE}=1.0V$ $I_C=10mA$	0.5		0.8	V

CE

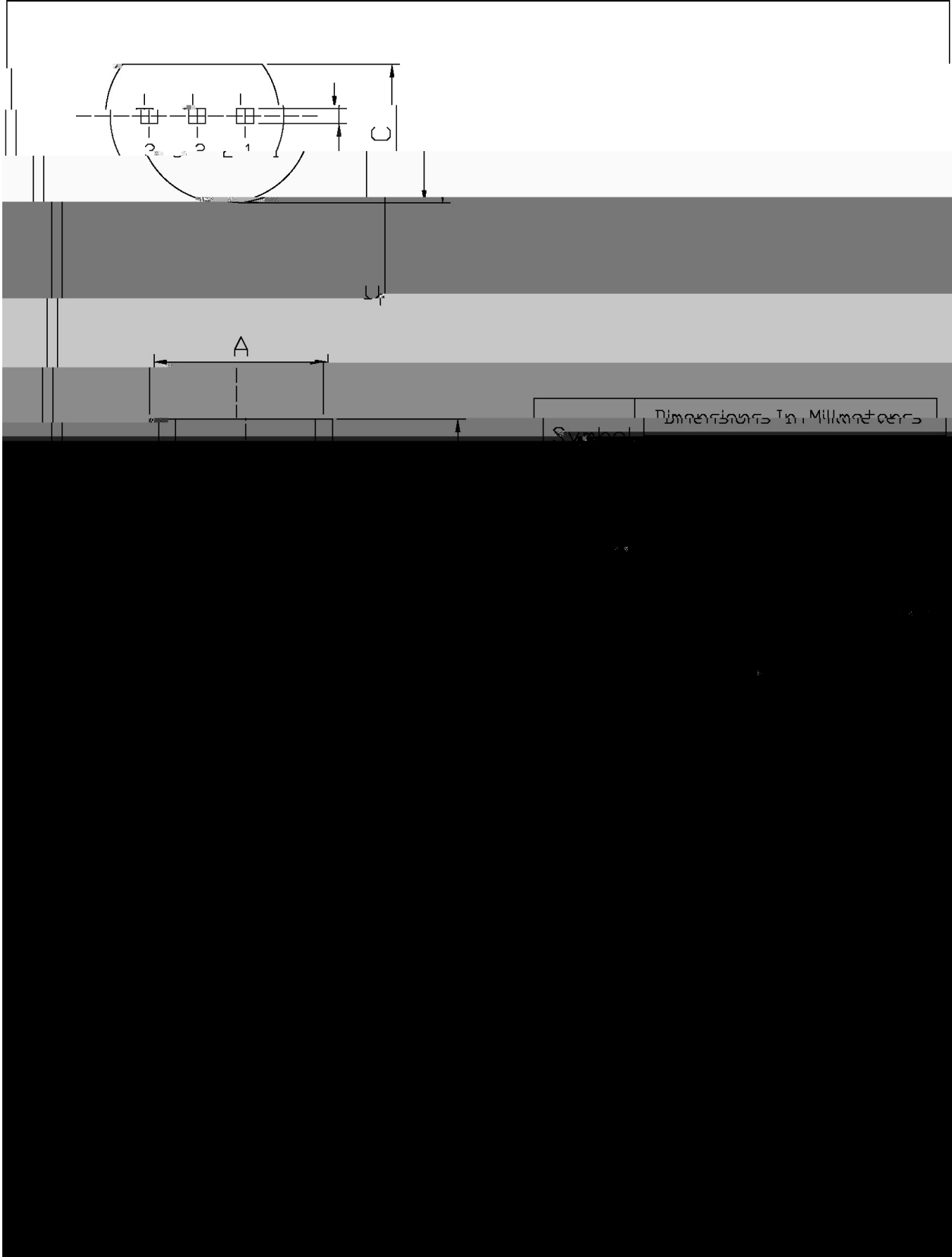
/ Electrical Characteristic Curve



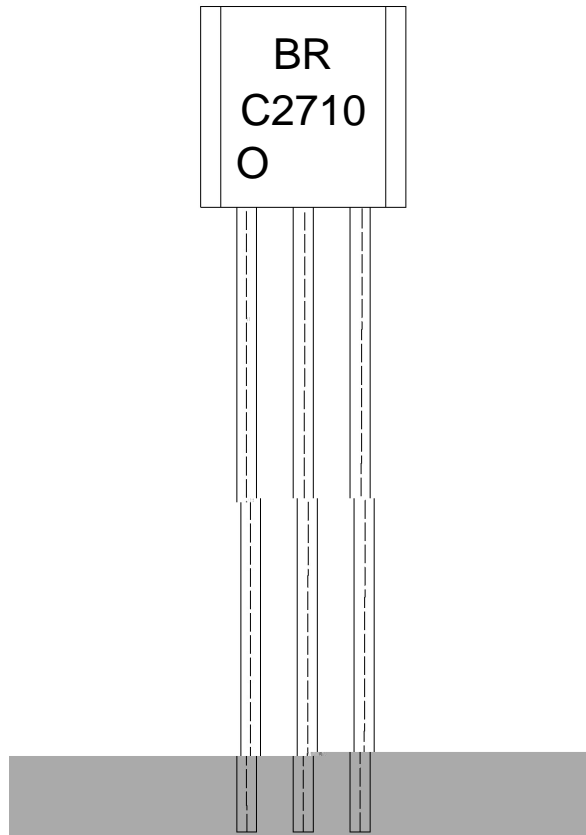
/ Package Dimensions

T0-92

Unit: mm



/ Marking Instructions



BR:

C2710

O:  $h_{FE}$

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Note:

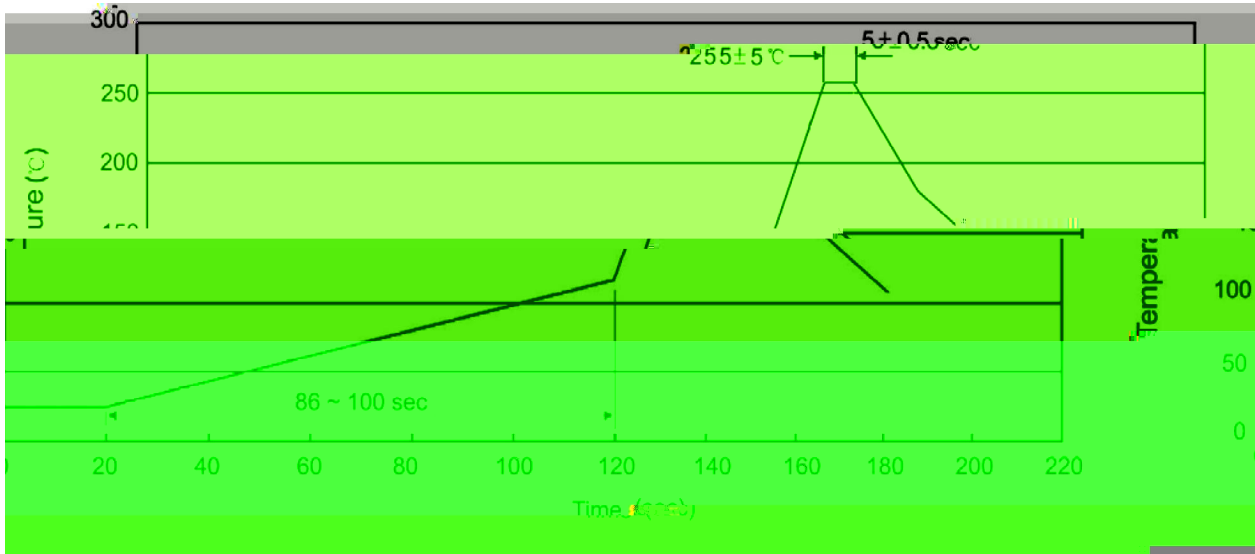
BR: Company Code.

C2710: Product Type.

O:  $h_{FE}$  Classifications Symbol

\*\*\*\*: Lot No. Code, code change with Lot No.

( ) / Temperature Profile for Dip Soldering(Pb-Free)



Note:

- |   |       |     |           |        |   |
|---|-------|-----|-----------|--------|---|
| 1 | 25    | 150 | 60        | 90sec; | 1.Preheating:25~150 , Time:60~90sec.    |
| 2 | 255±5 |     | 5±0.5sec; |        | 2.Peak Temp.:255±5 , Duration:5±0.5sec. |
| 3 |       | 2   | 10        | /sec.  | 3. Cooling Speed: 2~10 /sec.            |

/ Resistance to Soldering Heat Test Conditions

270±5                      10±1 sec.                      Temp:270±5                      Time:10±1 sec

/ Packaging SPEC.

/ BULK

Package Type 封装形式	Units 包装数量	Dimension 包装尺寸 (unit: mm3)
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